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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/729,710	12/05/2003	Yakov Belopolsky	FCI-2731/C3274A	4213
48580 7590 05/16/2007 WOODCOCK WASHBURN, LLP CIRA CENTRE, 12TH FLOOR 2929 ARCH STREET PHILADELPHIA, PA 19104-2891			EXAMINER BUI, HUNG S	
			ART UNIT 2841	PAPER NUMBER
			MAIL DATE 05/16/2007	DELIVERY MODE PAPER

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.

<b>Office Action Summary</b>	<b>Application No.</b> 10/729,710	<b>Applicant(s)</b> BELOPOLSKY, YAKOV	
	<b>Examiner</b> Hung S. Bui	<b>Art Unit</b> 2841	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) ☒ Responsive to communication(s) filed on 22 February 2007.
- 2a) ☒ This action is **FINAL**.                      2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) ☒ Claim(s) 1-19 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 1-19 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☒ The drawing(s) filed on 12 May 2003 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All    b) ☐ Some \* c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- \* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- |   |   |
|---|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)   | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)  | 5) <input type="checkbox"/> Notice of Informal Patent Application                       |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08)<br>Paper No(s)/Mail Date <u>02/27/2007</u> . | 6) <input type="checkbox"/> Other: _____  |

## DETAILED ACTION

### ***Claim Rejections - 35 USC § 103***

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. Claims 1-2, 4 and 6-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Szu [US 6,196,871] in view of Noschese [US 4,767,344] and Findeis et al. [US 6,203,690].

**Regarding claim 1**, Szu discloses an electronic assembly, comprising a printed circuit board substrate (34, figure 2, column 2, line 59) including a retentive through hole (36, figures 2, 4a and 4b, column 3, line 64), a plurality of lands (38, figure 2, column 3, line 39), and an electrical connector (10, figure 2, column 2, line 54), the electronic connector comprising:

- a housing (10, figure 2);
- a plurality of solder masses (16, figure 2, column 3, line 4) extending from a surface of the housing for electrically connecting the electrical connector to the land of the circuit substrate (34, figure 2); and
- a retention structure (18, figure 2, column 3, line 12) extending from the surface of the housing spaced apart from the plurality of solder masses (figures 4a-4b) and positioned within the thorough holes.

Szu discloses the instant claimed invention except for the retentive structure is made with a base material and a plating material disposed over at least a portion of the base material; and the retention structure having a cross-sectional area smaller than an area of the through hole so that a clearance exists between the retentive structure and a periphery of the through hole; wherein at least some of the plating material separates from the base material at a reflow temperature of the plurality of solder masses and combines with a solder composition within the through hole so that the solder composition and the plating material, upon cooling, form a bond between the printed circuit substrate and the retentive structure.

Findeis et al. disclose a chip carrier (10, figures 1-3) having at least one retentive element (16) being mounted thereon, wherein the retentive element comprises a base material (Nickel layer 22) and a plating material (Gold layer 24) covered the base material (figures 1-3).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the retentive element design of Findeis et al. for the retentive structure of Szu, for the purpose of providing thermal conductivity between the socket/housing and the circuit board.

Noschese discloses an electronic assembly (figures 3-4) having a housing (22, figure 3, column 4, line 23); a circuit substrate (32, figure 3, column 4, line 49) including a retentive through hole (a through hole including a copper plating 46 as shown in figures 3-4), at least one retentive structure (26, figures 3-4, column 4, line 13) extending from the surface of the housing, wherein the retentive structure is positioned

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in the retentive through hole and has a cross-sectional area smaller than an area of the through hole so that a clearance exists between the retentive structure and periphery of the through hole (see figures 3-4), and the retentive through hole is filled with a solder composition material (column 4, lines 56-65).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the retentive structure design of Noschese in Szu, as modified, for the purpose of permanently mounting the housing socket onto the circuit substrate.

**Regarding claim 2**, Szu, as modified, disclose the instant claimed invention except for the specific reflow temperature.

Noschese discloses the physical property (as solder mass resin) being a melting with temperature (column 5, lines 44-59).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use a specific reflow temperature of the solder masses for mounting a socket/housing to the printed circuit, as suggested by Noschese, which is intended to be used by manufacturing.

**Regarding claim 4**, Szu, as modified, disclose the instant claimed invention except for the retentive structure is made with a base material and a plating material disposed over at least a portion of the base material.

Findeis et al. disclose a chip carrier (10, figures 1-3) having at least one retentive element (16) being mounted thereon, wherein the retentive element comprises a base

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material (Nickel layer 22) and a plating material (Gold layer 24) covered the base material (figures 1-3).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the retentive element design of Findeis et al. for the retentive structure of Szu, as modified, for the purpose of providing thermal conductivity between the socket/housing and the circuit board.

**Regarding claim 6-7**, Szu, as modified, disclose the instant claimed invention except for the specific volume percentage of material associated with the solder.

The specific volume percentage of material associated with the solder would have been an obvious design consideration based on the specific fabrication technique used to mount the electrical component.

3. Claims 8-11 and 16-17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Szu [US 6,196,871] in view of Noschese [US 4,767,344].

**Regarding claim 8**, Szu discloses an electronic assembly, comprising a printed circuit board substrate (34, figure 2, column 2, line 59) including a retentive through hole (36, figures 2, 4a and 4b, column 3, line 64), a plurality of lands (38, figure 2, column 3, line 39), and an electrical connector (10, figure 2, column 2, line 54), the electronic connector comprising:

- a housing (10, figure 2);

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- a plurality of solder masses (16, figure 2, column 3, line 4) extending from a surface of the housing for electrically connecting the electrical connector to the land of the circuit substrate (34, figure 2); and
- a retention structure (18, figure 2, column 3, line 12) extending from the surface of the housing spaced apart from the plurality of solder masses (figures 4a-4b) and positioned within the thorough holes.

Szu discloses the instant claimed invention except for the retention structure having a cross-sectional area smaller than an area of the through hole so that a clearance exists between the retentive structure and a periphery of the through hole; and made with a material that combines with a solder composition within the through hole and enables continued affixation of the electrical connector to a circuit substrate at temperatures sufficient to initiate reflow of the plurality of solder masses.

Noschese discloses an electronic assembly (figures 3-4) having a housing (22, figure 3, column 4, line 23); a circuit substrate (32, figure 3, column 4, line 49) including a retentive through hole (a through hole including a copper plating 46 as shown in figures 3-4), at least one retentive structure (26, figures 3-4, column 4, line 13) extending from the surface of the housing, wherein the retentive structure is positioned in the retentive through hole and has a cross-sectional area smaller than an area of the through hole so that a clearance exists between the retentive structure and periphery of the through hole (see figures 3-4), and the retentive through hole is filled with a solder composition material (column 4, lines 56-65).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the retentive structure design of Noschese in Szu, for the purpose of permanently mounting the housing socket onto the circuit substrate.

**Regarding claim 9**, Szu discloses an electronic assembly, comprising a printed circuit board substrate (34, figure 2, column 2, line 59) including a retentive through hole (36, figures 2, 4a and 4b, column 3, line 64), a plurality of lands (38, figure 2, column 3, line 39), and an electrical connector (10, figure 2, column 2, line 54), the electronic connector comprising:

- a housing (10, figure 2);
- a retention structure (18, figure 2, column 3, line 12) extending from the surface of the housing and being received by the through hole formed in the substrate for effecting a non-electrical connection with a circuit substrate.

Szu discloses the instant claimed invention except for the retention structure made with material that alters a physical property of a solder composition in contact with the retentive structure within the through hole at a reflow temperature of such a solder composition.

Noschese discloses an electronic assembly (figures 3-4) having a housing (22, figure 3, column 4, line 23); a circuit substrate (32, figure 3, column 4, line 49) including a retentive through hole (a through hole including a copper plating 46 as shown in figures 3-4), at least one retentive structure (26, figures 3-4, column 4, line 13) extending from the surface of the housing, wherein the retentive structure is inserted



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into the retentive through hole and being filled with a solder composition material (column 4, lines 56-65).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the retentive structure design of Noschese in Szu, for the purpose of permanently mounting the housing socket onto the circuit substrate.

**Regarding claim 10-11**, Szu discloses the instant claimed invention except for the specific reflow temperature.

Noschese discloses the physical property (as solder mass resin) being a melting with temperature (column 5, lines 44-59).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use a specific reflow temperature of the solder masses for mounting a socket/housing to the printed circuit which is intended to be used by manufacturing.

**Regarding claim 16**, Szu, as modified, disclose a plurality of solder masses (16, figure 2, column 3, line 4) extending from a surface of the housing for electrically connection to a circuit substrate (34, figure 2).

**Regarding claim 17**, Szu discloses an electrical connector (10, figure 2, column 2, line 54), comprising:

- a housing (10, figure 2);
- a plurality of solder masses (16, figure 2, column 3, line 4) extending from a surface of the housing for electrically connecting the electrical connector to a circuit substrate (34, figure 2); and

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- a retention structure (18, figure 2, column 3, line 12) extending from the surface of the housing spaced apart from the plurality of solder masses (figures 4a-4b) and positioned within the thorough holes.

Szu discloses the instant claimed invention except for the retention structure comprising a material that combines with a solder composition within the through hole and after initial affixation of the solder masses with the circuit substrate, affixation at the solder masses is compromised, due to an elevated temperature, prior to affixation at the retentive structure.

Noschese discloses an electrical connector (figures 3-4) having a housing (22, figure 3, column 4, line 23); a circuit substrate (32, figure 3, column 4, line 49) including a retentive through hole (a through hole including a copper plating 46 as shown in figures 3-4), at least one retentive structure (26, figures 3-4, column 4, line 13) extending from the surface of the housing, wherein the retentive structure is positioned in the retentive through hole and filled with a solder composition material (column 4, lines 56-65).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the retentive structure design of Noschese in Szu, for the purpose of permanently mounting the housing socket onto the circuit substrate.

4. Claims 3, 5 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Szu, as modified, as applied to claim 1 above, and further in view of Melton et al. [US 5,086,966].

**Regarding claims 3, 5 and 13**, Szu, as modified, disclose the instant claimed invention except for the plating material/join being formed of palladium.

Melton et al. disclose the use of palladium in a solder composition for mounting an electrical component (column 1, line 65 – column 2, line 14).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use gold/palladium with the solder composition of Szu, in view of Noschese and Findeis et al., as suggested by Melton et al., the purpose of improving solder wetting.

5. Claims 12 and 14 are rejected under 35 U.S.C. 103(a) as being unpatentable over Szu, as modified, as applied to claim 9 above, and further in view of Findeis et al. [US 6,203,690].

**Regarding claims 12 and 14**, Szu, as modified, disclose the instant claimed invention except for the retentive structure is made with a base material and a plating material disposed over at least a portion of the base material.

Findeis et al. disclose a chip carrier (10, figures 1-3) having at least one retentive element (16) being mounted thereon, wherein the retentive element comprises a base material (Nickel layer 22) and a plating material (Gold layer 24) covered the base material (figures 1-3).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use the retentive element design of Findeis et al. for the retentive

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structure of Szu, as modified, for the purpose of providing thermal conductivity between the socket/housing and the circuit board.

6. Claim 15 is rejected under 35 U.S.C. 103(a) as being unpatentable over Szu, as modified, as applied to claim 9 above, and further in view of Melton et al. [US 5,086,966].

**Regarding claim 15**, Szu, as modified, disclose the instant claimed invention except for the plating material/join being formed of palladium.

Melton et al. disclose the use of palladium in a solder composition for mounting an electrical component (column 1, line 65 – column 2, line 14).

It would have been obvious to one of ordinary skill in the art at the time the invention was made to use gold/palladium with the solder composition of Szu, in view of Noschese and Findeis et al., as suggested by Melton et al., the purpose of improving solder wetting.

7. Claim 19 is rejected under 35 U.S.C. 103(a) as being unpatentable over Szu, as modified, as applied to claim 1 above, and further in view of Zeng et al. [US 6,434,016].

Regarding claim 19, Szu, as modified, disclose the instant claimed invention except for an additional electronic connector being mounted another side of the circuit substrate.

Zeng et al. disclose a printed circuit board (200, figure 2a) having at least one electronic component (205, figure 2a) being mounted on a first side thereon, and at

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least a second component (220, figure 2a) being mounted on a second side of the printed circuit board.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to mount an additional electronic connector on another side of the circuit substrate of Szu, as modified, as suggested by Zeng et al., for the purpose of providing additional socket can be used within the circuit substrate.

### ***Response to Arguments***

8. Applicant's arguments with respect to claims 1-19 have been considered but are moot in view of the new ground(s) of rejection.

### ***Conclusion***

9. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of

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the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

10. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hung S. Bui whose telephone number is (571) 272-2102. The examiner can normally be reached on Monday-Friday 8:30AM-6:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Dean A Reichard can be reached on (571) 272-1984. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

05/12/2007  
**Hung Bui**  
**Art Unit 2841**



**TUAN T. DINH**  
**PRIMARY EXAMINER**